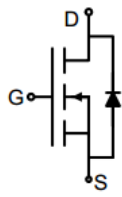
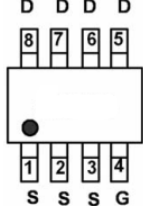
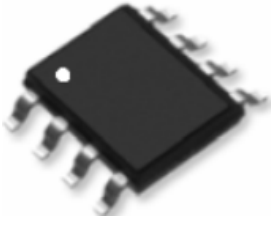


N-Channel Enhancement Mode Power MOSFET

Description The G16N03S uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.		 Schematic diagram  Marking and pin assignment  SOP-8	
General Features • V_{DS} 30V • I_D (at $V_{GS} = 10V$) 12A • $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 10mΩ • $R_{DS(ON)}$ (at $V_{GS} = 5V$) < 15mΩ • 100% Avalanche Tested • RoHS Compliant			
Application • Power switch • DC/DC converters			
Device	Package	Marking	Packaging
G16N03S	SOP-8	G16N03	4000pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Continuous Drain Current	I_D	12	A
Pulsed Drain Current (note1)	I_{DM}	44	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	2.5	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	$^\circ\text{C}$

Thermal Resistance

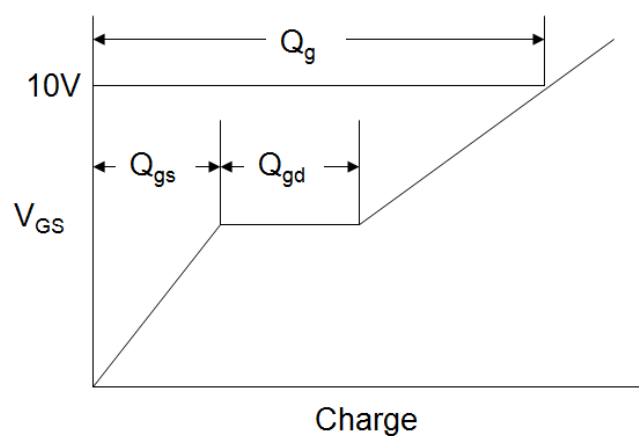
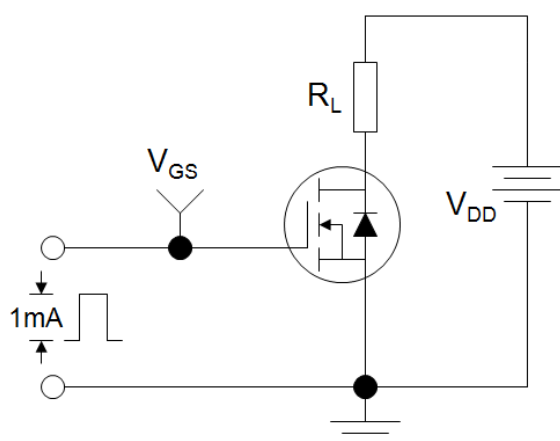
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	50	$^\circ\text{C/W}$

Specifications T _j = 25°C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V	--	--	1	μA
Gate-Source Leakage	I _{GSS}	V _{GS} = ±20V	--	--	±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	1.35	2.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 10A	--	6.7	10	mΩ
		V _{GS} = 5V, I _D = 10A	--	8.3	15	
Forward Transconductance	g _{FS}	V _{DS} =10V,I _D =10A	--	25	--	S
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 15V, f = 1.0MHz	--	950	--	pF
Output Capacitance	C _{oss}		--	280	--	
Reverse Transfer Capacitance	C _{rss}		--	160	--	
Total Gate Charge	Q _g	V _{DD} = 15V, I _D = 10A, V _{GS} = 10V	--	16.6	--	nC
Gate-Source Charge	Q _{gs}		--	3.6	--	
Gate-Drain Charge	Q _{gd}		--	3	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15V, I _D = 10A, R _G = 1.8Ω	--	10	--	ns
Turn-on Rise Time	t _r		--	8	--	
Turn-off Delay Time	t _{d(off)}		--	30	--	
Turn-off Fall Time	t _f		--	5	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I _S	T _C = 25°C	--	--	12	A
Body Diode Voltage	V _{SD}	T _J = 25°C, I _{SD} = 10A, V _{GS} = 0V	--	--	1.2	V

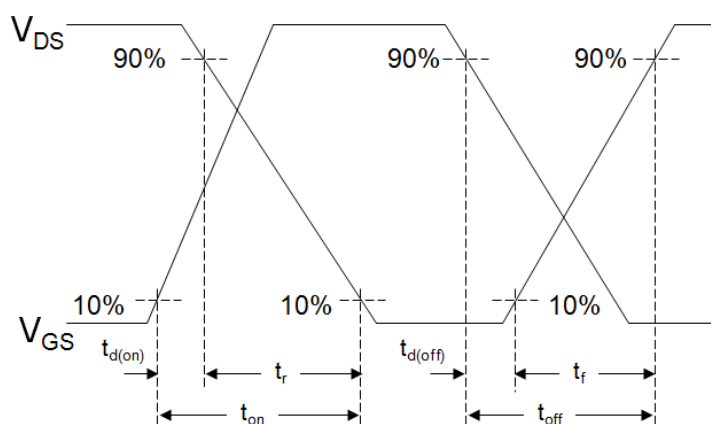
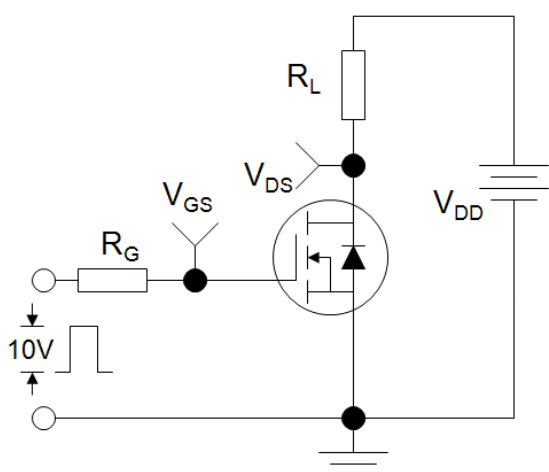
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G

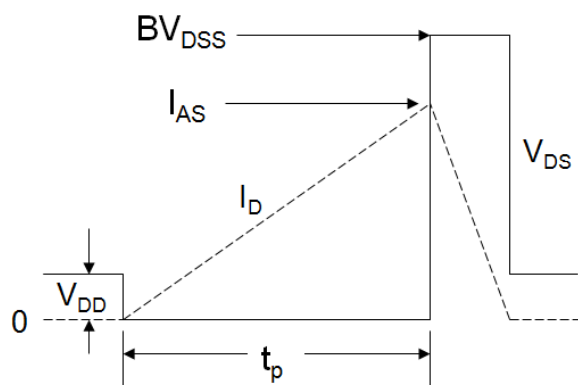
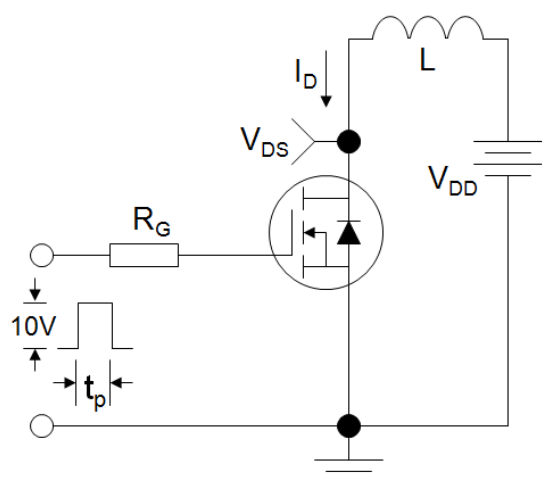
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

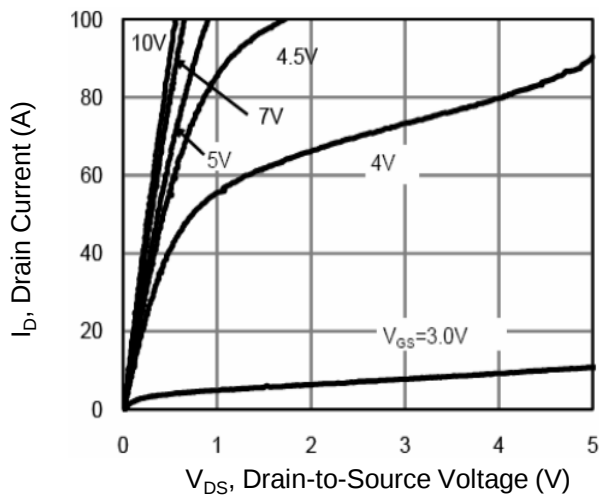


Figure 2. Transfer Characteristics

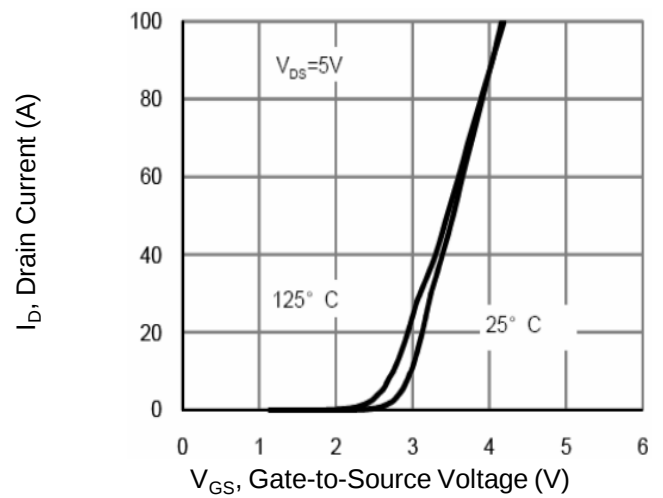


Figure 3. Gate Charge

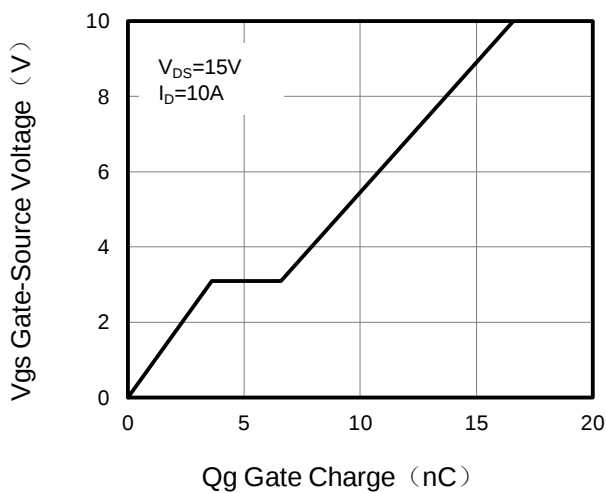


Figure 4. Drain Source On Resistance

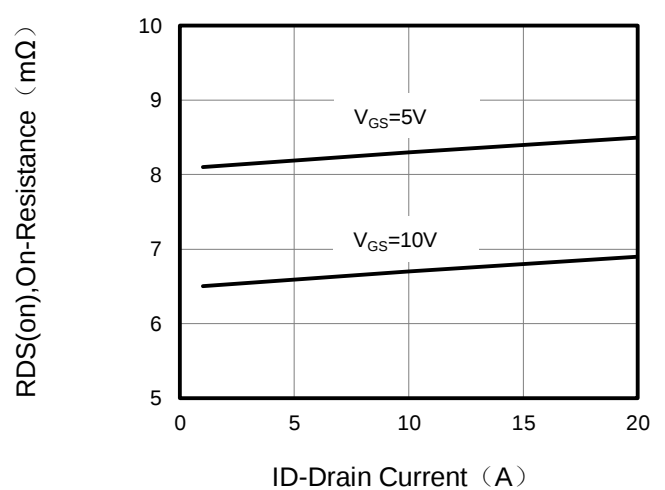


Figure 5. Capacitance

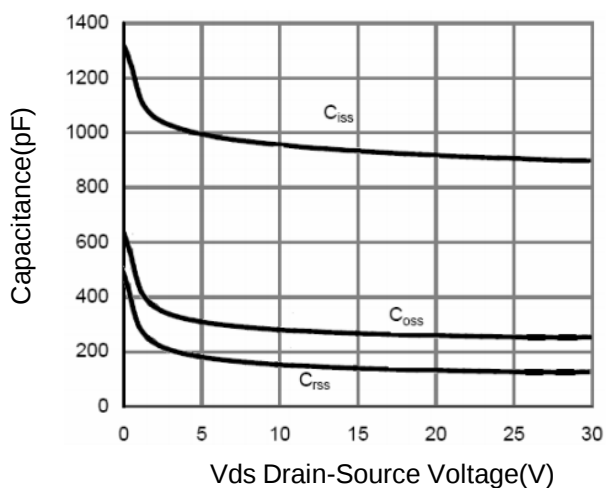
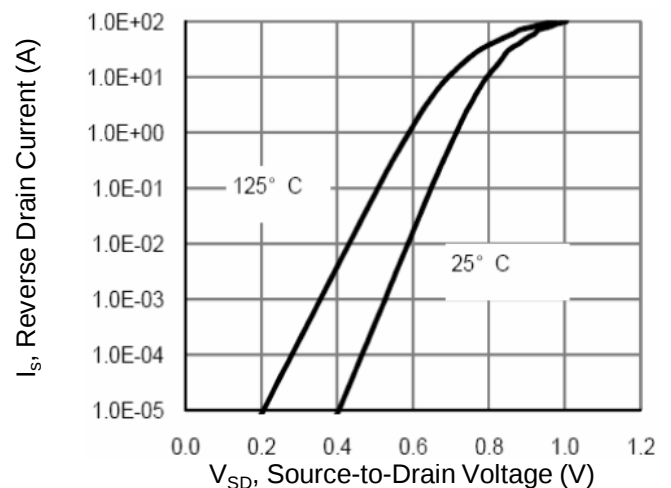


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

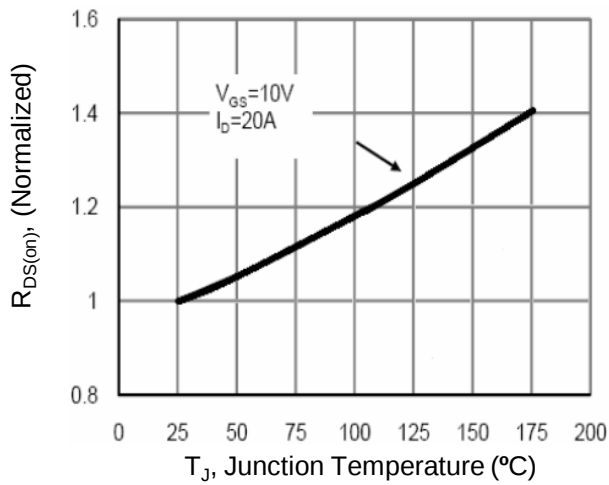


Figure 8. Safe Operation Area

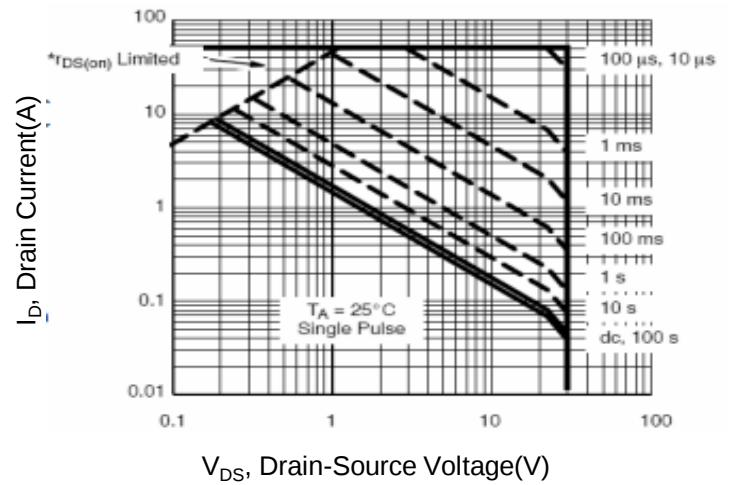
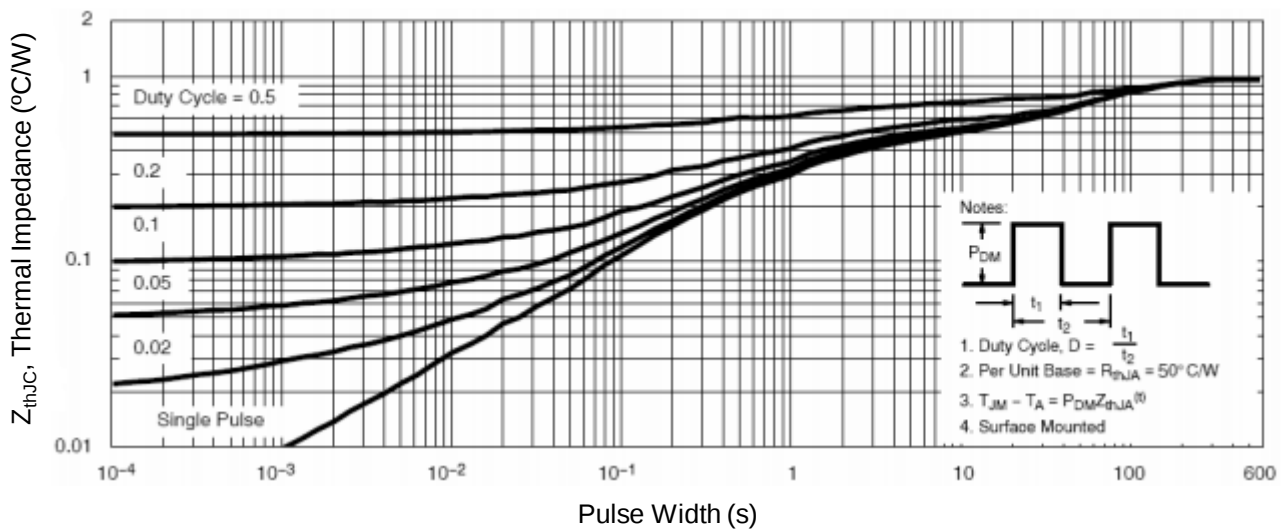
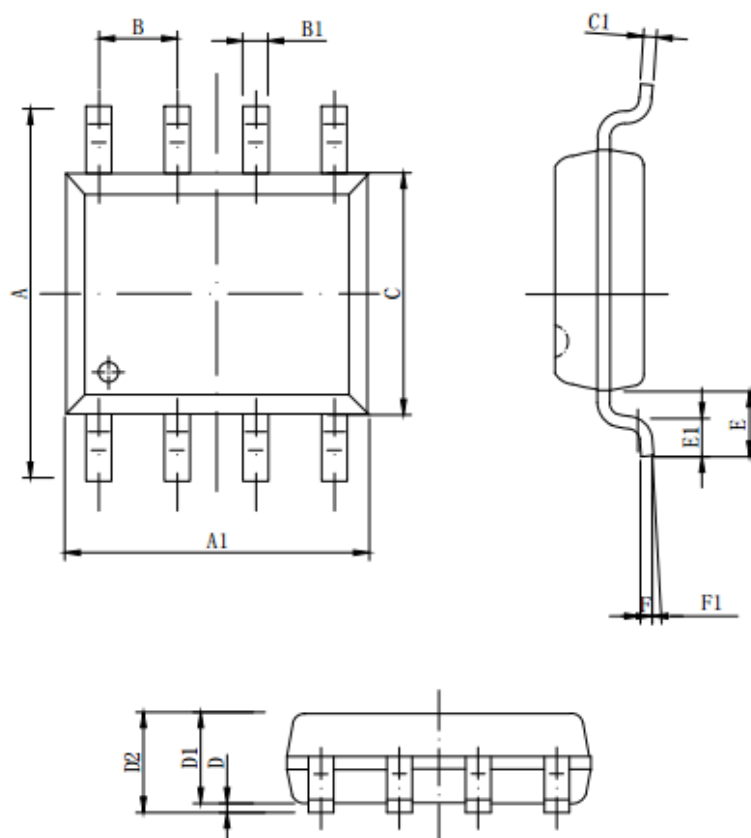


Figure 9. Normalized Maximum Transient



SOP-8 Package Information



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	5.800	6.000	6.200
A1	4.800	4.900	5.000
B	1.270BSC		
B1	0.35 ^{8x}	0.40 ^{8x}	0.45 ^{8x}
C	3.780	3.880	3.980
C1	--	0.203	0.253
D	0.050	0.150	0.250
D1	1.350	1.450	1.550
D2	1.500	1.600	1.700
D2	1.500	1.600	1.700
E	1.060REF		
E1	0.400	0.700	0.100
F	0.250BSC		
F1	2°	4°	6°